

CLEAN VERSION INCORPORATING CHANGES MADE

In The Specification:

Please replace the first paragraph of the Specification entitled Technical Field with the following:

Technical Field

4 This application is a national stage application of international application PCT/US99/07653 filed April 6, 1999. This application is a continuation-in-part of application Serial No. 09/056,436 filed April 7, 1998, currently pending, which is a continuation-in-part of U.S. application 09/008,769 filed January 19, 1998, now U.S. Patent 6,097,581 which is a continuation-in-part of U.S. Application 08/841,940, filed April 8, 1997, now U.S. Patent 5,909,305. This application also claims the benefit of U.S. Provisional Application No. 60/101,511 filed September 23, 1998 and U.S. Provisional Application No. 60/103,759 filed October 9, 1998. The present invention relates to electronic component carriers used in the manufacture of electronic equipment. More specifically, the invention relates to component carrier substrates used to protect electronic components from mechanical stresses associated with their handling and coupling within electronic equipment. The component carrier substrates also provide electrical interference shielding and improved thermal characteristics.
